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Details

E·XFI

Product Status	Active
Core Processor	AVR
Core Size	32-Bit Single-Core
Speed	66MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, IrDA, LINbus, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, I ² S, POR, PWM, WDT
Number of I/O	123
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 16x12b; D/A 4x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at32uc3c0512c-alur

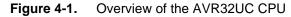
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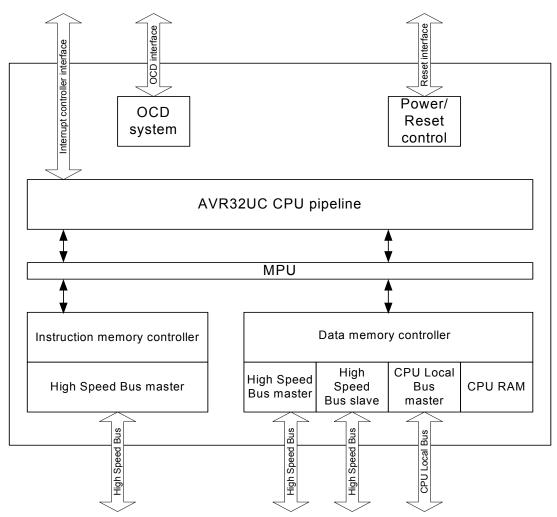
Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Table 2-1.	Configuration Summary
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Feature	AT32UC3C0512C/ AT32UC3C0256C/ AT32UC3C0128C/ AT32UC3C064C	AT32UC3C1512C/ AT32UC3C1256C/ AT32UC3C1128C/ AT32UC3C164C	AT32UC3C2512C/ AT32UC3C2256C/ AT32UC3C2128C/ AT32UC3C264C			
Analog Comparators	4	4	2			
JTAG		1				
aWire	1					
Max Frequency	66 MHz					
Package	LQFP144	TQFP100	TQFP64/QFN64			







4.3.1 Pipeline Overview

AVR32UC has three pipeline stages, Instruction Fetch (IF), Instruction Decode (ID), and Instruction Execute (EX). The EX stage is split into three parallel subsections, one arithmetic/logic (ALU) section, one multiply (MUL) section, and one load/store (LS) section.

Instructions are issued and complete in order. Certain operations require several clock cycles to complete, and in this case, the instruction resides in the ID and EX stages for the required number of clock cycles. Since there is only three pipeline stages, no internal data forwarding is required, and no data dependencies can arise in the pipeline.

Figure 4-2 on page 28 shows an overview of the AVR32UC pipeline stages.



Reg #	Address	Name	Function
90	360	MPUPSR2	MPU Privilege Select Register region 2
91	364	MPUPSR3	MPU Privilege Select Register region 3
92	368	MPUPSR4	MPU Privilege Select Register region 4
93	372	MPUPSR5	MPU Privilege Select Register region 5
94	376	MPUPSR6	MPU Privilege Select Register region 6
95	380	MPUPSR7	MPU Privilege Select Register region 7
96	384	MPUCRA	Unused in this version of AVR32UC
97	388	MPUCRB	Unused in this version of AVR32UC
98	392	MPUBRA	Unused in this version of AVR32UC
99	396	MPUBRB	Unused in this version of AVR32UC
100	400	MPUAPRA	MPU Access Permission Register A
101	404	MPUAPRB	MPU Access Permission Register B
102	408	MPUCR	MPU Control Register
103	412	SS_STATUS	Secure State Status Register
104	416	SS_ADRF	Secure State Address Flash Register
105	420	SS_ADRR	Secure State Address RAM Register
106	424	SS_ADR0	Secure State Address 0 Register
107	428	SS_ADR1	Secure State Address 1 Register
108	432	SS_SP_SYS	Secure State Stack Pointer System Register
109	436	SS_SP_APP	Secure State Stack Pointer Application Register
110	440	SS_RAR	Secure State Return Address Register
111	444	SS_RSR	Secure State Return Status Register
112-191	448-764	Reserved	Reserved for future use
192-255	768-1020	IMPL	IMPLEMENTATION DEFINED

Table 4 9 m Deviatere (Centinued)

4.5 **Exceptions and Interrupts**

In the AVR32 architecture, events are used as a common term for exceptions and interrupts. AVR32UC incorporates a powerful event handling scheme. The different event sources, like Illegal Op-code and interrupt requests, have different priority levels, ensuring a well-defined behavior when multiple events are received simultaneously. Additionally, pending events of a higher priority class may preempt handling of ongoing events of a lower priority class.

When an event occurs, the execution of the instruction stream is halted, and execution is passed to an event handler at an address specified in Table 4-4 on page 38. Most of the handlers are placed sequentially in the code space starting at the address specified by EVBA, with four bytes between each handler. This gives ample space for a jump instruction to be placed there, jumping to the event routine itself. A few critical handlers have larger spacing between them, allowing the entire event routine to be placed directly at the address specified by the EVBA-relative offset generated by hardware. All interrupt sources have autovectored interrupt service routine (ISR) addresses. This allows the interrupt controller to directly specify the ISR address as an address



relative to EVBA. The autovector offset has 14 address bits, giving an offset of maximum 16384 bytes. The target address of the event handler is calculated as (EVBA | event_handler_offset), not (EVBA + event_handler_offset), so EVBA and exception code segments must be set up appropriately. The same mechanisms are used to service all different types of events, including interrupt requests, yielding a uniform event handling scheme.

An interrupt controller does the priority handling of the interrupts and provides the autovector offset to the CPU.

4.5.1 System Stack Issues

Event handling in AVR32UC uses the system stack pointed to by the system stack pointer, SP_SYS, for pushing and popping R8-R12, LR, status register, and return address. Since event code may be timing-critical, SP_SYS should point to memory addresses in the IRAM section, since the timing of accesses to this memory section is both fast and deterministic.

The user must also make sure that the system stack is large enough so that any event is able to push the required registers to stack. If the system stack is full, and an event occurs, the system will enter an UNDEFINED state.

4.5.2 Exceptions and Interrupt Requests

When an event other than *scall* or debug request is received by the core, the following actions are performed atomically:

- 1. The pending event will not be accepted if it is masked. The I3M, I2M, I1M, I0M, EM, and GM bits in the Status Register are used to mask different events. Not all events can be masked. A few critical events (NMI, Unrecoverable Exception, TLB Multiple Hit, and Bus Error) can not be masked. When an event is accepted, hardware automatically sets the mask bits corresponding to all sources with equal or lower priority. This inhibits acceptance of other events of the same or lower priority, except for the critical events listed above. Software may choose to clear some or all of these bits after saving the necessary state if other priority schemes are desired. It is the event source's responsability to ensure that their events are left pending until accepted by the CPU.
- 2. When a request is accepted, the Status Register and Program Counter of the current context is stored to the system stack. If the event is an INT0, INT1, INT2, or INT3, registers R8-R12 and LR are also automatically stored to stack. Storing the Status Register ensures that the core is returned to the previous execution mode when the current event handling is completed. When exceptions occur, both the EM and GM bits are set, and the application may manually enable nested exceptions if desired by clearing the appropriate bit. Each exception handler has a dedicated handler address, and this address uniquely identifies the exception source.
- 3. The Mode bits are set to reflect the priority of the accepted event, and the correct register file bank is selected. The address of the event handler, as shown in Table 4-4 on page 38, is loaded into the Program Counter.

The execution of the event handler routine then continues from the effective address calculated.

The *rete* instruction signals the end of the event. When encountered, the Return Status Register and Return Address Register are popped from the system stack and restored to the Status Register and Program Counter. If the *rete* instruction returns from INT0, INT1, INT2, or INT3, registers R8-R12 and LR are also popped from the system stack. The restored Status Register contains information allowing the core to resume operation in the previous execution mode. This concludes the event handling.



4.5.3 Supervisor Calls

The AVR32 instruction set provides a supervisor mode call instruction. The *scall* instruction is designed so that privileged routines can be called from any context. This facilitates sharing of code between different execution modes. The *scall* mechanism is designed so that a minimal execution cycle overhead is experienced when performing supervisor routine calls from time-critical event handlers.

The *scall* instruction behaves differently depending on which mode it is called from. The behaviour is detailed in the instruction set reference. In order to allow the *scall* routine to return to the correct context, a return from supervisor call instruction, *rets*, is implemented. In the AVR32UC CPU, *scall* and *rets* uses the system stack to store the return address and the status register.

4.5.4 Debug Requests

The AVR32 architecture defines a dedicated Debug mode. When a debug request is received by the core, Debug mode is entered. Entry into Debug mode can be masked by the DM bit in the status register. Upon entry into Debug mode, hardware sets the SR.D bit and jumps to the Debug Exception handler. By default, Debug mode executes in the exception context, but with dedicated Return Address Register and Return Status Register. These dedicated registers remove the need for storing this data to the system stack, thereby improving debuggability. The Mode bits in the Status Register can freely be manipulated in Debug mode, to observe registers in all contexts, while retaining full privileges.

Debug mode is exited by executing the *retd* instruction. This returns to the previous context.

4.5.5 Entry Points for Events

Several different event handler entry points exist. In AVR32UC, the reset address is 0x80000000. This places the reset address in the boot flash memory area.

TLB miss exceptions and *scall* have a dedicated space relative to EVBA where their event handler can be placed. This speeds up execution by removing the need for a jump instruction placed at the program address jumped to by the event hardware. All other exceptions have a dedicated event routine entry point located relative to EVBA. The handler routine address identifies the exception source directly.

AVR32UC uses the ITLB and DTLB protection exceptions to signal a MPU protection violation. ITLB and DTLB miss exceptions are used to signal that an access address did not map to any of the entries in the MPU. TLB multiple hit exception indicates that an access address did map to multiple TLB entries, signalling an error.

All interrupt requests have entry points located at an offset relative to EVBA. This autovector offset is specified by an interrupt controller. The programmer must make sure that none of the autovector offsets interfere with the placement of other code. The autovector offset has 14 address bits, giving an offset of maximum 16384 bytes.

Special considerations should be made when loading EVBA with a pointer. Due to security considerations, the event handlers should be located in non-writeable flash memory, or optionally in a privileged memory protection region if an MPU is present.

If several events occur on the same instruction, they are handled in a prioritized way. The priority ordering is presented in Table 4-4 on page 38. If events occur on several instructions at different locations in the pipeline, the events on the oldest instruction are always handled before any events on any younger instruction, even if the younger instruction has events of higher priority



AT32UC3C

Priority	Handler Address	Name	Event source	Stored Return Address
1	0x80000000	Reset	External input	Undefined
2	Provided by OCD system	OCD Stop CPU	OCD system	First non-completed instruction
3	EVBA+0x00	Unrecoverable exception	Internal	PC of offending instruction
4	EVBA+0x04	TLB multiple hit	MPU	PC of offending instruction
5	EVBA+0x08	Bus error data fetch	Data bus	First non-completed instruction
6	EVBA+0x0C	Bus error instruction fetch	Data bus	First non-completed instruction
7	EVBA+0x10	NMI	External input	First non-completed instruction
8	Autovectored	Interrupt 3 request	External input	First non-completed instruction
9	Autovectored	Interrupt 2 request	External input	First non-completed instruction
10	Autovectored	Interrupt 1 request	External input	First non-completed instruction
11	Autovectored	Interrupt 0 request	External input	First non-completed instruction
12	EVBA+0x14	Instruction Address	CPU	PC of offending instruction
13	EVBA+0x50	ITLB Miss	MPU	PC of offending instruction
14	EVBA+0x18	ITLB Protection	MPU	PC of offending instruction
15	EVBA+0x1C	Breakpoint	OCD system	First non-completed instruction
16	EVBA+0x20	Illegal Opcode	Instruction	PC of offending instruction
17	EVBA+0x24	Unimplemented instruction	Instruction	PC of offending instruction
18	EVBA+0x28	Privilege violation	Instruction	PC of offending instruction
19	EVBA+0x2C	Floating-point	UNUSED	
20	EVBA+0x30	Coprocessor absent	Instruction	PC of offending instruction
21	EVBA+0x100	Supervisor call	Instruction	PC(Supervisor Call) +2
22	EVBA+0x34	Data Address (Read)	CPU	PC of offending instruction
23	EVBA+0x38	Data Address (Write)	CPU	PC of offending instruction
24	EVBA+0x60	DTLB Miss (Read)	MPU	PC of offending instruction
25	EVBA+0x70	DTLB Miss (Write)	MPU	PC of offending instruction
26	EVBA+0x3C	DTLB Protection (Read)	MPU	PC of offending instruction
27	EVBA+0x40	DTLB Protection (Write)	MPU	PC of offending instruction
28	EVBA+0x44	DTLB Modified	UNUSED	

Table 4-4. Priority and Handler Addresses for Events



The following GPIO registers are mapped on the local bus:

 Table 5-4.
 Local bus mapped GPIO registers

Port	Register	Mode	Local Bus Address	Access
А	Output Driver Enable Register (ODER)	WRITE	0x40000040	Write-only
		Mode Address	Write-only	
		CLEAR	0x40000048	Write-only
		TOGGLE	0x4000004C	Write-only
	Output Value Register (OVR)	WRITE	0x40000050	Write-only
		SET	0x40000054	Write-only
		CLEAR	0x40000058	Write-only
		TOGGLE	0x4000005C	Write-only
	Pin Value Register (PVR)	-	0x40000060	Read-only
В	Output Driver Enable Register (ODER)	WRITE	0x40000140	Write-only
		SET 0x400 CLEAR 0x400	0x40000144	Write-only
		CLEAR	0x40000148	Write-only
		TOGGLE	0x4000014C	Write-only
	Output Value Register (OVR)	WRITE	0x40000150	Write-only
		SET	0x40000154	Write-only
		CLEAR	0x40000158	Write-only
		TOGGLE	0x4000015C	Write-only
	Pin Value Register (PVR)	-	0x40000160	Read-only
С	Output Driver Enable Register (ODER)	WRITE	0x40000240	Write-only
		SET	0x40000244	Write-only
		CLEAR	0x40000248	Write-only
		TOGGLE	0x4000024C	Write-only
	Output Value Register (OVR)	WRITE	0x40000250	Write-only
		SET	0x40000254	Write-only
		CLEAR	0x40000258	Write-only
		TOGGLE	0x4000025C	Write-only
	Pin Value Register (PVR)	-	0x40000260	Read-only



6. Supply and Startup Considerations

6.1 Supply Considerations

6.1.1 Power Supplies

The AT32UC3C has several types of power supply pins:

- VDDIO pins (VDDIO1, VDDIO2, VDDIO3): Power I/O lines. Two voltage ranges are available: 5V or 3.3V nominal. The VDDIO pins should be connected together.
- VDDANA: Powers the Analog part of the device (Analog I/Os, ADC, ACs, DACs). 2 voltage ranges available: 5V or 3.3V nominal.
- VDDIN_5: Input voltage for the 1.8V and 3.3V regulators. Two Voltage ranges are available: 5V or 3.3V nominal.
- VDDIN_33:
 - USB I/O power supply
 - if the device is 3.3V powered: Input voltage, voltage is 3.3V nominal.
 - if the device is 5V powered: stabilization for the 3.3V voltage regulator, requires external capacitors
- VDDCORE: Stabilization for the 1.8V voltage regulator, requires external capacitors.
- GNDCORE: Ground pins for the voltage regulators and the core.
- GNDANA: Ground pin for Analog part of the design
- GNDPLL: Ground pin for the PLLs
- GNDIO pins (GNDIO1, GNDIO2, GNDIO3): Ground pins for the I/O lines. The GNDIO pins should be connected together.

See "Electrical Characteristics" on page 50 for power consumption on the various supply pins.

For decoupling recommendations for the different power supplies, please refer to the schematic checklist.

6.1.2 Voltage Regulators

The AT32UC3C embeds two voltage regulators:

- One 1.8V internal regulator that converts from VDDIN_5 to 1.8V. The regulator supplies the output voltage on VDDCORE.
- One 3.3V internal regulator that converts from VDDIN_5 to 3.3V. The regulator supplies the USB pads on VDDIN_33. If the USB is not used or if VDDIN_5 is within the 3V range, the 3.3V regulator can be disabled through the VREG33CTL field of the VREGCTRL SCIF register.

6.1.3 Regulators Connection

The AT32UC3C supports two power supply configurations.

- 5V single supply mode
- 3.3V single supply mode

6.1.3.1 5V Single Supply Mode

In 5V single supply mode, the 1.8V internal regulator is connected to the 5V source (VDDIN_5 pin) and its output feeds VDDCORE.



6.2 Startup Considerations

This chapter summarizes the boot sequence of the AT32UC3C. The behavior after power-up is controlled by the Power Manager. For specific details, refer to the Power Manager chapter.

6.2.1 Starting of clocks

At power-up, the BOD33 and the BOD18 are enabled. The device will be held in a reset state by the power-up circuitry, until the VDDIN_33 (resp. VDDCORE) has reached the reset threshold of the BOD33 (resp BOD18). Refer to the Electrical Characteristics for the BOD thresholds. Once the power has stabilized, the device will use the System RC Oscillator (RCSYS, 115KHz typical frequency) as clock source. The BOD18 and BOD33 are kept enabled or are disabled according to the fuse settings (See the Fuse Setting section in the Flash Controller chapter).

On system start-up, the PLLs are disabled. All clocks to all modules are running. No clocks have a divided frequency, all parts of the system receive a clock with the same frequency as the internal RC Oscillator.

6.2.2 Fetching of initial instructions

After reset has been released, the AVR32UC CPU starts fetching instructions from the reset address, which is 0x8000_0000. This address points to the first address in the internal Flash.

The internal Flash uses VDDIO voltage during read and write operations. It is recommended to use the BOD33 to monitor this voltage and make sure the VDDIO is above the minimum level (3.0V).

The code read from the internal Flash is free to configure the system to use for example the PLLs, to divide the frequency of the clock routed to some of the peripherals, and to gate the clocks to unused peripherals.



7.6 Oscillator Characteristics

7.6.1 Oscillator (OSC0 and OSC1) Characteristics

7.6.1.1 Digital Clock Characteristics

The following table describes the characteristics for the oscillator when a digital clock is applied on XIN0 or XIN1.

 Table 7-7.
 Digital Clock Characteristics

Symbol	Parameter	Conditions	Min	Тур	Мах	Units
f _{CPXIN}	XIN clock frequency				50	MHz
t _{CPXIN}	XIN clock period		20			ns
t _{CHXIN}	XIN clock high half-priod		0.4 x t _{CPXIN}		0.6 x t _{CPXIN}	ns
t _{CLXIN}	XIN clock low half-priod		0.4 x t _{CPXIN}		0.6 x t _{CPXIN}	ns
C _{IN}	XIN input capacitance			2		pF

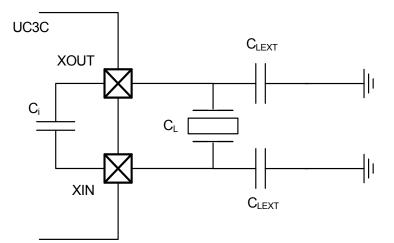
7.6.1.2 Crystal Oscillator Characteristics

The following table describes the characteristics for the oscillator when a crystal is connected between XIN and XOUT as shown in Figure 7-2. The user must choose a crystal oscillator where the crystal load capacitance C_L is within the range given in the table. The exact value of C_L can be found in the crystal datasheet. The capacitance of the external capacitors (C_{LEXT}) can then be computed as follows:

$$C_{LEXT} = 2(C_L - C_i) - C_{PCB}$$

where C_{PCB} is the capacitance of the PCB and C_i is the internal equivalent load capacitance.

Figure 7-2. Oscillator Connection





7.8.6 Analog to Digital Converter (ADC) and sample and hold (S/H) Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Units
		12-bit resolution mode, $V_{VDDANA} = 3V$			1.2	
		10-bit resolution mode, $V_{VDDANA} = 3V$			1.6	
£	ADC clock	8-bit resolution mode, $V_{VDDANA} = 3V$			2.2	MHz
f _{ADC}	frequency	12-bit resolution mode, $V_{VDDANA} = 4.5V$			1.5	
		10-bit resolution mode, $V_{VDDANA} = 4.5V$			2	_
		8-bit resolution mode, $V_{VDDANA} = 4.5V$			2.4	
		ADC cold start-up			1	ms
t _{STARTUP}	Startup time	ADC hot start-up	= 4.5V 2.4 1 24 + 2, 6 8	ADC clock cycles		
	Conversion time	(ADCIFA.SEQCFGn.SRES)/2 + 2, ADCIFA.CFG.SHD = 1	6		8	ADC clock
t _{CONV}	(latency)	InductionInduction (V_VDDANA = 100 C)10-bit resolution mode, V_VDDANA = 4.5V8-bit resolution mode, V_VDDANA = 4.5VADC cold start-upADC hot start-upADC hot start-up(ADCIFA.SEQCFGn.SRES)/2 + 2, ADCIFA.CFG.SHD = 1(ADCIFA.SEQCFGn.SRES)/2 + 3, ADCIFA.CFG.SHD = 0(ADCIFA.SEQCFGn.SRES)/2 + 3, ADCIFA.CFG.SHD = 012-bit resolution, ADC clock = 1.2 MHz, V_VDDANA = 3Vnoughput rateADC clock = 1.6 MHz, V_VDDANA = 3V12-bit resolution, ADC clock = 1.6 MHz, V_VDDANA = 3V	9	cycles		
					1.2	
		,			1.6	MODO
	i nrougnput rate	12-bit resolution, ADC clock = 1.5 MHz, V _{VDDANA} = 4.5V			1.5	– MSPS
		10-bit resolution, ADC clock = 2 MHz, V _{VDDANA} = 4.5V			2	

Table 7-27. ADC and S/H characteristics

Table 7-28. ADC Reference Voltage

Symbol	Parameter	Conditions	Min	Тур	Max	Unit s
N/	ADCREF0 input voltage range	5V Range	1		3.5	V
V _{ADCREF0}	ADCREFO Input voltage lange	3V Range	1		V _{VDDANA} -0.7	v
M		5V Range	1		3.5	V
V _{ADCREF1} ADCREF1 input voltage	ADCREFT Input voltage lange	3V Range	1		V _{VDDANA} -0.7	v
		5V Range - Voltage reference applied on ADCREFP	1		3.5	- V
V _{ADCREFP}	ADCREFP input voltage	3V Range - Voltage reference applied on ADCREFP	1		3.5 V _{VDDANA} -0.7	V
V _{ADCREFN}	ADCREFN input voltage	Voltage reference applied on ADCREFN		GNDANA		V
	Internal 1V reference			1.0		V
	Internal 0.6*VDDANA reference			0.6*V _{VDDANA}		V



Symbol	Parameter	Conditions	Min	Тур	Max	Units
RES	Resolution	Differential mode,			10	Bit
INL	Integral Non-Linearity	$V_{VDDANA} = 5V,$			1.5	LSB
DNL	Differential Non-Linearity	$V_{ADCREF0} = 3V,$			1.5	LSB
	Offset error	ADCFIA.SEQCFGn.SRES = 1, S/H gain from 1 to 16	-25		25	mV
	Gain error	$(F_{adc} = 1.5MHz)$	-15		15	mV

Table 7-36. ADC and S/H Transfer Characteristics (Continued)10-bit Resolution Mode and S/H gain from 1 to 16⁽¹⁾

Note: 1. The measures are done without any I/O activity on VDDANA/GNDANA power domain.

7.8.7 Digital to Analog Converter (DAC) Characteristics

 Table 7-37.
 Channel Conversion Time and DAC Clock

Symbol	Parameter	Conditions	Min	Тур	Max	Units
f _{DAC}	DAC clock frequency				1	MHz
t _{STARTUP}	Startup time				3	μs
t _{CONV}	Conversion time (latency)	No S/H enabled, internal DAC			1	μs
		One S/H			1.5	μs
		Two S/H			2	μs
	Throughput rate				1/t _{CONV}	MSPS

Table 7-38. External Voltage Reference Input

Symbol	Parameter	Conditions	Min	Тур	Мах	Units
VDACREF	DACREF input voltage range		1.2		V _{VDDANA} -0.7	V

Table 7-39. DAC Outputs

Symbol	Parameter	Conditions	Min	Тур	Max	Units	
	Output range	with external DAC reference	0.2		VDACREF	V	
	Oulput lange	with internal DAC reference	0.2		V _{VDDANA} -0.7		
C _{LOAD}	Output capacitance		0		100	pF	
R _{LOAD}	Output resitance		2			kΩ	



7.9 Timing Characteristics

7.9.1 Startup, Reset, and Wake-up Timing

The startup, reset, and wake-up timings are calculated using the following formula:

$$t = t_{CONST} + N_{CPU} \times t_{CPU}$$

Where t_{CONST} and N_{CPU} are found in Table 7-44. t_{CONST} is the delay relative to RCSYS, t_{CPU} is the period of the CPU clock. If another clock source than RCSYS is selected as CPU clock the startup time of the oscillator, $t_{OSCSTART}$, must be added to the wake-up time in the stop, deepstop, and static sleep modes. Please refer to the source for the CPU clock in the "Oscillator Characteristics" on page 57 for more details about oscillator startup times.

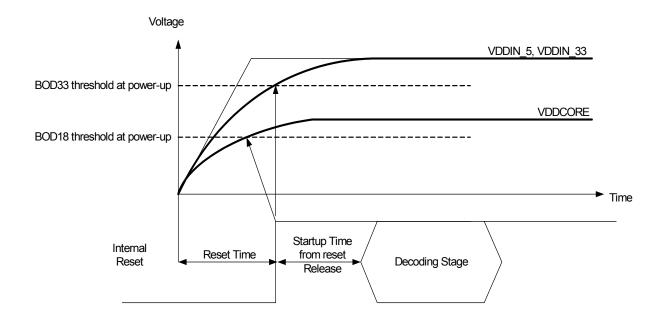
Table 7-44. Maximum Reset and Wake-up Timing

Parameter		Measuring	Max <i>t_{CONST}</i> (in µs)	${\rm Max}\; N_{CPU}$
Startup time from power-up, using regulator		VDDIN_5 rising (10 mV/ms) Time from V_{VDDIN_5} =0 to the first instruction entering the decode stage of CPU. VDDCORE is supplied by the internal regulator.	2600	0
Startup time fr	rom reset release	Time from releasing a reset source (except POR, BOD18, and BOD33) to the first instruction entering the decode stage of CPU.1240		0
	Idle		0	19
	Frozen		268	209
	Standby	From wake-up event to the first instruction entering	268	209
Wake-up	Stop	the decode stage of the CPU.	268+ t _{OSCSTART}	212
	Deepstop		268+ t _{OSCSTART}	212
	Static		268+ t _{OSCSTART}	212



AT32UC3C

Figure 7-5. Startup and Reset Time



7.9.2 RESET_N characteristics

Symbol	Parameter	Condition	Min.	Тур.	Max.	Units
t _{RESET}	RESET_N minimum pulse length		2 * T _{RCSYS}			clock cycles



Figure 7-12. SPI Master Mode With (CPOL= 0 and NCPHA= 1) or (CPOL= 1 and NCPHA= 0)

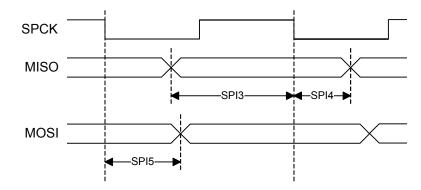


Table 7-48. SPI Timing, Master Mode⁽¹⁾

Symbol	Parameter	Conditions	Min	Мах	Units
SPI0	MISO setup time before SPCK rises		28.5+ (t _{CLK_SPI})/2		ns
SPI1	MISO hold time after SPCK rises		0		ns
SPI2	SPCK rising to MOSI delay	external		10.5	ns
SPI3	MISO setup time before SPCK falls	capacitor = 40pF	28.5 + (t _{CLK_SPI})/2		ns
SPI4	MISO hold time after SPCK falls		0		ns
SPI5	SPCK falling to MOSI delay			10.5	ns

Note: 1. These values are based on simulation and characterization of other AVR microcontrollers manufactured in the same process technology. These values are not covered by test limits in production.

Maximum SPI Frequency, Master Output

The maximum SPI master output frequency is given by the following formula:

$$f_{SPCKMAX} = MIN(f_{PINMAX}, \frac{1}{SPIn})$$

Where *SPIn* is the MOSI delay, SPI2 or SPI5 depending on CPOL and NCPHA. f_{PINMAX} is the maximum frequency of the SPI pins. Please refer to the I/O Pin Characteristics section for the maximum frequency of the pins.

Maximum SPI Frequency, Master Input

The maximum SPI master input frequency is given by the following formula:

$$f_{SPCKMAX} = \frac{1}{SPIn + t_{VALID}}$$

Where *SPIn* is the MISO setup and hold time, SPI0 + SPI1 or SPI3 + SPI4 depending on CPOL and NCPHA. t_{VALID} is the SPI slave response time. Please refer to the SPI slave datasheet for t_{VALID} .



TWIM and TWIS user interface registers. Please refer to the TWIM and TWIS sections for more information.

Table 7-50. **TWI-Bus Timing Requirements**

			Minimum		Maxir	num		
Symbol	Parameter	Mode	Requirement	Device	Requirement	Device	Unit	
	TWOK and TWD rise time	Standard ⁽¹⁾	-		1000		20	
t _r	TWCK and TWD rise time	Fast ⁽¹⁾	20 + 0	.1 C _b	30	0	ns	
		Standard ⁽¹⁾	-		300			
t _f	TWCK and TWD fall time	Fast ⁽¹⁾	20 + 0	.1 C _b	30	0	ns	
		Standard ⁽¹⁾	4.0	4				
t _{HD-STA}	(Repeated) START hold time	Fast ⁽¹⁾	0.6	t _{clkpb}	-	μs		
		Standard ⁽¹⁾	4.7					
t _{SU-STA}	(Repeated) START set-up time	Fast ⁽¹⁾	0.6	t _{clkpb}	-		μS	
t _{SU-STO}	STOP set-up time	Standard ⁽¹⁾	4.0		-		μs	
		Fast ⁽¹⁾	0.6	4t _{clkpb}				
	Data hold time	Standard ⁽¹⁾	- 0.3 ⁽²⁾ 2t _{clkpb} -	01	3.45	22		
t _{HD-DAT}		Fast ⁽¹⁾		0.9	??	μS		
	Data act un time	Standard ⁽¹⁾	250	01	-		ns	
t _{SU-DAT-I2C}	Data set-up time	Fast ⁽¹⁾	100	2t _{clkpb}				
t _{SU-DAT}		-	-	t _{clkpb}	-		-	
	TWOK LOW period	Standard ⁽¹⁾	4.7	44				
t _{LOW-I2C}	TWCK LOW period	Fast ⁽¹⁾	1.3	4t _{clkpb}	-		μs	
t _{LOW}		-	-	t _{clkpb}	-		-	
	TWCK LICH paried	Standard ⁽¹⁾	4.0		-			
t _{HIGH}	TWCK HIGH period	Fast ⁽¹⁾	0.6	8t _{clkpb}			μS	
£		Standard ⁽¹⁾		1	100	1	ld le	
f _{TWCK}	TWCK frequency	Fast ⁽¹⁾	-		400	^{12t} clkpb	kHz	

Notes: 1. Standard mode: $f_{TWCK} \le 100 \text{ kHz}$; fast mode: $f_{TWCK} > 100 \text{ kHz}$. 2. A device must internally provide a hold time of at least 300 ns for TWD with reference to the falling edge of TWCK.

Notations:

C_b = total capacitance of one bus line in pF

 t_{clkpb} = period of TWI peripheral bus clock

 $t_{prescaled}$ = period of TWI internal prescaled clock (see chapters on TWIM and TWIS)

The maximum $t_{HD;DAT}$ has only to be met if the device does not stretch the LOW period ($t_{LOW-I2C}$) of TWCK.



7.9.6 JTAG Timing

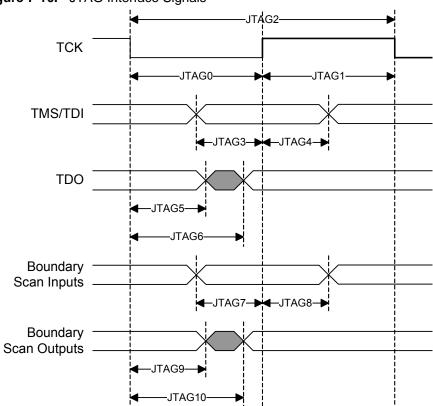


Figure 7-16. JTAG Interface Signals

Table 7	7-51.	JTAG	Timings ⁽¹⁾
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Symbol	Parameter	Conditions	Min	Max	Units
JTAG0	TCK Low Half-period		21.5		ns
JTAG1	TCK High Half-period		8.5		ns
JTAG2	TCK Period		29		ns
JTAG3	TDI, TMS Setup before TCK High		6.5		ns
JTAG4	TDI, TMS Hold after TCK High	external	0		ns
JTAG5	TDO Hold Time	capacitor =	12.5		ns
JTAG6	TCK Low to TDO Valid	40pF		21.5	ns
JTAG7	Boundary Scan Inputs Setup Time		0		ns
JTAG8	Boundary Scan Inputs Hold Time		4.5		ns
JTAG9	Boundary Scan Outputs Hold Time		11		ns
JTAG10	TCK to Boundary Scan Outputs Valid			18	ns

Note: 1. These values are based on simulation and characterization of other AVR microcontrollers manufactured in the same process technology. These values are not covered by test limits in production.



Symbol	Parameter	Conditions	Min	Units
SMC ₃₇	NWE rising to A2-A25 valid		8.7	
SMC ₃₈	NWE rising to NBS0/A0 valid	V _{VDD} = 3.0V, drive strength of the pads set to the lowest,	7.6	
SMC ₄₀	NWE rising to A1/NBS2 change		8.7	
SMC ₄₂	NWE rising to NCS rising		8.4	ns
SMC ₄₃	Data Out valid before NWE rising	external capacitor = 40pF	(nwe pulse length - 1) * tcpsмc - 1.2	
SMC ₄₄	Data Out valid after NWE rising		8.4	
SMC ₄₅	NWE pulse width		nwe pulse length * tcpsmc - 0	

 Table 7-56.
 SMC Write Signals with No Hold Settings (NWE Controlled only)⁽¹⁾

Note: 1. These values are based on simulation and characterization of other AVR microcontrollers manufactured in the same process technology. These values are not covered by test limits in production.

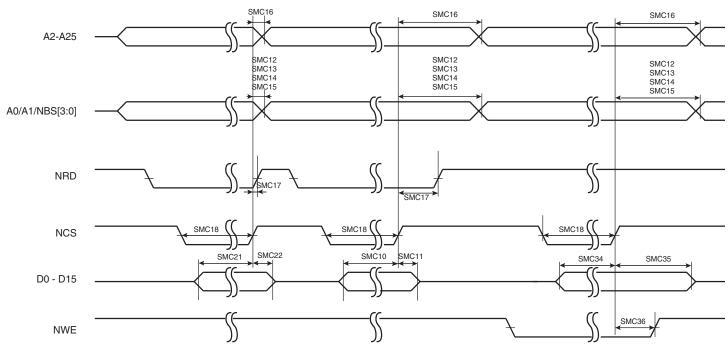


Figure 7-17. SMC Signals for NCS Controlled Accesses



10.2.10 TWIS

10.2.11 USBC

1 Clearing the NAK bit before the BTF bit is set locks up the TWI bus

When the TWIS is in transmit mode, clearing the NAK Received (NAK) bit of the Status Register (SR) before the end of the Acknowledge/Not Acknowledge cycle will cause the TWIS to attempt to continue transmitting data, thus locking up the bus. **Fix/Workaround**

Clear SR.NAK only after the Byte Transfer Finished (BTF) bit of the same register has been set.

2 TWIS stretch on Address match error

When the TWIS stretches TWCK due to a slave address match, it also holds TWD low for the same duration if it is to be receiving data. When TWIS releases TWCK, it releases TWD at the same time. This can cause a TWI timing violation. **Fix/Workaround**

None.

3 TWALM forced to GND

The TWALM pin is forced to GND when the alternate function is selected and the TWIS module is enabled.

Fix/Workaround

None.

1 UPINRQx.INRQ field is limited to 8-bits

In Host mode, when using the UPINRQx.INRQ feature together with the multi-packet mode to launch a finite number of packet among multi-packet, the multi-packet size (located in the descriptor table) is limited to the UPINRQx.INRQ value multiply by the pipe size. **Fix/Workaround**

UPINRQx.INRQ value shall be less than the number of configured multi-packet.

2 In USB host mode, downstream resume feature does not work (UHCON.RESUME=1). Fix/Workaround

None.

3 In host mode, the disconnection during OUT transition is not supported In USB host mode, a pipe can not work if the previous USB device disconnection has occurred during a USB transfer. Fix/Workaround

Reset the USBC (USBCON.USB=0 and =1) after a device disconnection (UHINT.DDISCI).

4 In USB host mode, entering suspend mode can fail

In USB host mode, entering suspend mode can fail when UHCON.SOFE=0 is done just after a SOF reception (UHINT.HSOFI).

Fix/Workaround

Check that UHNUM.FLENHIGH is below 185 in Full speed and below 21 in Low speed before clearing UHCON.SOFE.

5 In USB host mode, entering suspend mode for low speed device can fail when the USB freeze (USBCON.FRZCLK=1) is done just after UHCON.SOFE=0. Fix/Workaround

When entering suspend mode (UHCON.SOFE is cleared), check that USBFSM.DRDSTATE is not equal to three before freezing the clock (USBCON.FRZCLK=1).





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